COM4

COM4 SIM Specification

Global IoT SIM cards with access to over 750 different networks in over 190 countries
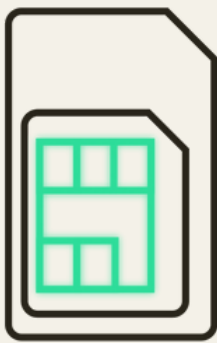
Access to all available RAT-types from one SIM card
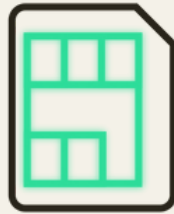2G, 3G, 4G, 5G, NB-IoT, LTE-M
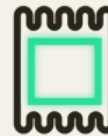
Physical SIM form factors
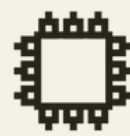
SIM | eSIM | iSIM

Mini SIM
25 x 15 mm

Micro SIM
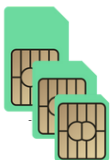15 x 12 mm

Nano SIM
12.3 x 8.8 mm

eSIM
6 x 5 mm

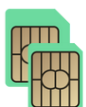**iSIM**
Fraction of mm²

Global IoT MFF2 SIM

- MFF2 (QFN8 package, 5x6 mm, ETSI TS 102.671)
- eUICC support
- Delivered in standardised tape reel of 500
- Operating temperature: -40 to +105°C
- Shock tolerance up to 1500G
- Vibration tolerance 20G, 20-2000 Hz
- Humidity tolerance 85°C, 85% humidity for minimum 1000 hours

Global IoT Plastic SIM Industrial

- Triple cut (2FF/3FF/4FF)
- Optional eUICC support
- Operating temperature: -25 to +85°C
- Humidity tolerance 85°C, 85% humidity for minimum 1000 hours

Global IoT Plastic SIM Industrial High Tolerance

- 2FF & 3FF
- eUICC support
- Operating temperature: -40 to +105°C
- Shock tolerance up to 1500G
- Humidity tolerance 85°C, 85% humidity for minimum 1000 hours

Features

Remote SIM Provisioning (eUICC): SGP.02 compliant

Java CardTM 3.0.5 Classic Edition Specification

Hardware specifications

ISO 7816 / ETSI TS 102.221 for electrical characteristics and communication protocol.

Voltage: class A (5V), class B (3V) and C (1.8V) supply voltages

Data retention time: 15 years (TS 102.671)

YOUR TRUE PARTNER
FOR IOT CONNECTIVITY

Compliance

ISO 7816 / ETSI TS 102.221 for electrical characteristics and communication protocol.

Quality process : ISO 9001

RoHS, REACH, Halogen-Free

TS 31.919: 2G/3G Java CardTM Application Programming Interface (API) based applet interworking; (V8.0.0)

ETSI TS 101.220: ETSI numbering system for telecommunication application providers; (V9.3.0)

TS 31.101: UICC-Terminal Interface; Physical and Logical Characteristics; (V15.2.0)

TS 31.111: USIM Application Toolkit (USAT); (V15.6.0)

TS 31.900: SIM/USIM internal and external interworking aspects; (V16.0.0)

Global IoT MFF2 SIM pin-out and dimensions